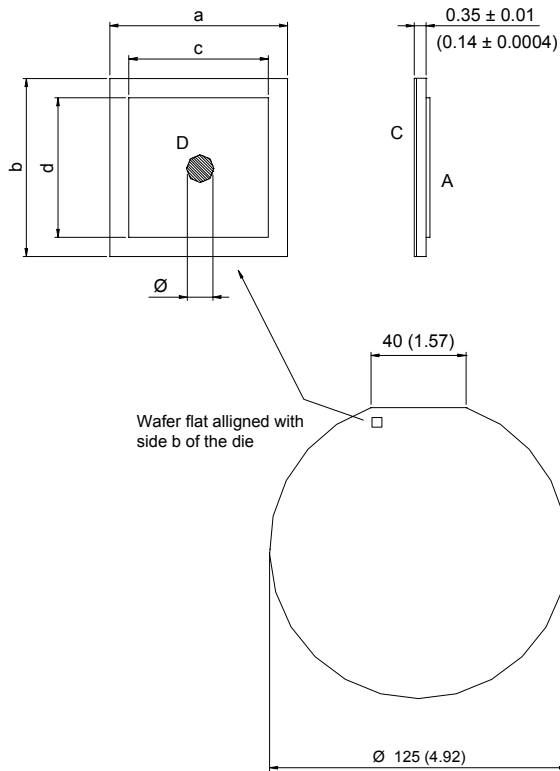


International
IOR Rectifier

SC275.....5. Series

SCHOTTKY DIE 275 x 275 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

2. CONTROLLING DIMENSION: (INCH).

3. DIMENSIONS AND TOLERANCES:

$a = 6.98 \pm 0, - 0.05$
 $(0.27 \pm 0, - 0.002)$
 $b = 6.98 \pm 0, - 0.05$
 $(0.27 \pm 0, - 0.002)$
 $c = 6.48 \pm 0, - 0.003$
 $(0.25 \pm 0, - 0.0001)$
 $d = 6.48 \pm 0, - 0.003$
 $(0.25 \pm 0, - 0.0001)$
 $\varnothing = 0.7 \pm 0.1$
 (0.03 ± 0.004)

4. LETTER DESIGNATION:

A = Anode (Top Metal)
 C = Cathode (Back Metal)
 D = Reject Ink Dot (only on non-conforming dies)

5. SAWING:

Recommended Blade
 SEMITEC S1025 QS00 Blade

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
Contact factory for information.

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (μA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC275R015x5x	125	15	n.a. contact factory			
SC275S020x5x	150	20	n.a. contact factory			
SC275S030x5x	150	30	1350	550	0.55 @ 150A	TO-249AA
SC275S045x5x	150	45	n.a. contact factory			
SC275S060x5x	150	60	n.a. contact factory			
SC275H045x5x	175	45	n.a. contact factory			
SC275H100x5x	175	100	n.a. contact factory			
SC275H150x5x	175	150	n.a. contact factory			

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC275xxxxA5x	Bondable	–	Al/Si 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC275xxxxS5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

Device #	Description	Minimum Order Quantity Die in Sale Package
SC275xxxx5B	Inked Probed Unawn Wafer (Wafer in Box)	180
SC275xxxx5R	Probed Die in Tape & Reel	n.a.
SC275xxxx5P	Probed Die in Waffle Pack	366
SC275xxxx5F	Inked Probed Sawn Wafer on Film	180

Ordering Information Table

Device Code

SC	275	S	030	S	5	B
1	2	3	4	5	6	7

1

- Schottky Die

2

- Chip Dimension in Mils

3

- Process (see Electrical Characteristics Table)

4

- Voltage code: Code = V_{RRM}

5

- Chip surface metallization (see Mechanical Data Table)

6

- Wafer Diameter in inches

7

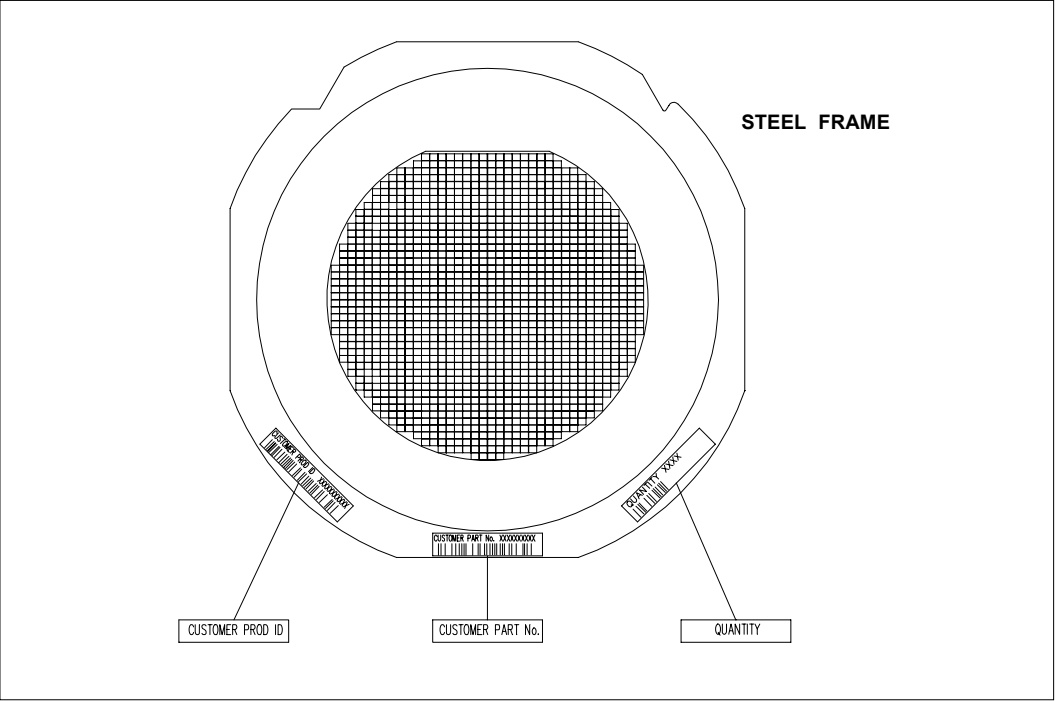
- Packaging (see Packaging Table)

H = 830 Process

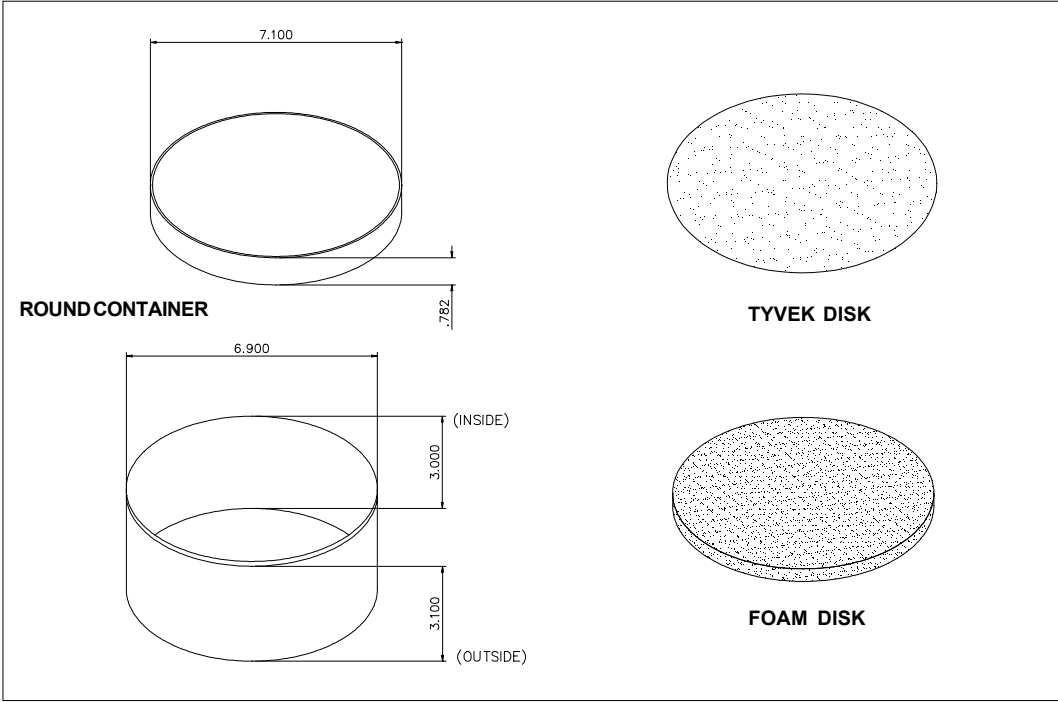
R = OR'ing Process

S = Standard Process

Wafer on Film



Wafer in Box



Die in Waffle Pack

